

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chung Chi Ko	02/25/2005
Syun Ming Jang	02/25/2005
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	10890622
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 2 source=assignment#page1.tif source=assignment#page2.tif	

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PATENT
REEL: 015785 FRAME: 0464

ASSIGNMENT

WHEREAS, I,

- | | | | |
|-----|----------------|----|--|
| (1) | Chung Chi Ko | of | No. 46, Jushan Rd., Jushan
Nantou, Taiwan, R.O.C. |
| (2) | Syun Ming Jeng | of | 7F, 83 N. Kuan-Hua St.
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

**Method of Preventing Photoresist Poisoning of a
Low-Dielectric-Constant Insulator**

for which I have executed applications for Letters Patent of the United States of America, Serial No. 60/521,703 filed June 21, 2004 and Serial No. 10/890,622 filed July 14, 2004;

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under said invention and said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the invention, and said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to TSMC, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor: Chung Chi Ko

Dated: 2/25/2005

Chung Chi Ko
Inventor Signature

Inventor: Syun Ming J^ang

Dated: 2/25/05

Syun Ming Jang
Inventor Signature